



US 20240179851A1

(19) **United States**

(12) **Patent Application Publication**
BELOVA-MAGRI et al.

(10) **Pub. No.: US 2024/0179851 A1**

(43) **Pub. Date: May 30, 2024**

(54) **MODIFIED COPPER SURFACE,
HETEROAROMATIC SILANE COMPOUNDS
AND THEIR USAGE FOR INCREASING
ADHESION STRENGTH BETWEEN COPPER
AND AN ORGANIC MATERIAL AND
REDUCING HALO AND WEDGE VOID
FORMATION**

(86) PCT No.: **PCT/EP2022/056360**

§ 371 (c)(1),

(2) Date: **Sep. 12, 2023**

(30) **Foreign Application Priority Data**

Mar. 12, 2021 (EP) 21162439.0

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Publication Classification

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(51) **Int. Cl.**

H05K 3/38 (2006.01)

H05K 3/00 (2006.01)

H05K 3/22 (2006.01)

H05K 3/26 (2006.01)

(52) **U.S. Cl.**

CPC **H05K 3/389** (2013.01); **H05K 3/0064**
(2013.01); **H05K 3/227** (2013.01); **H05K 3/26**
(2013.01); **H05K 3/385** (2013.01); **H05K**
2203/0315 (2013.01); **H05K 2203/0766**
(2013.01)

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(57) **ABSTRACT**

(21) Appl. No.: **18/550,145**

The present invention relates to a method for increasing adhesion strength between a surface of a copper, a copper alloy or a copper oxide and a surface of an organic material.

(22) PCT Filed: **Mar. 11, 2022**

